



# Nanophoto final meeting

## Summary of WP2: nc-Si deposition

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Via Anzani 42

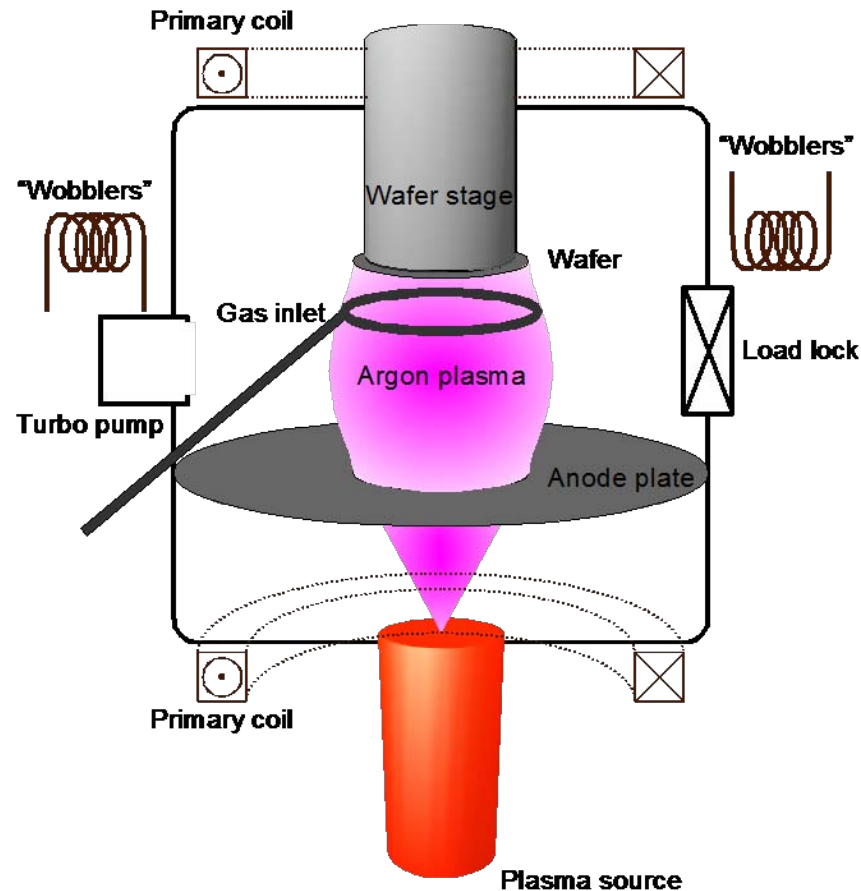
Como - Italy

# Outline

- **Low-energy plasma-enhanced CVD**  
working principle and prior knowledge
- **LEPECVD for nc-Si deposition**  
motivations and requirements
- **NANOPHOTO WP2 Objectives**
  - **Optimization of film microstructure**  
Crystalline/amorphous ratio, grain size
  - **Doping studies**  
Dopant incorporation in the nc-Si layer
  - **nc-Si growth for device optimization**  
Application of the optimized growth procedures to device fabrication
  - **Plasma diagnostics**  
Plasma diagnostic by mass spectrometry and Langmuir probe



# Low-energy plasma-enhanced CVD

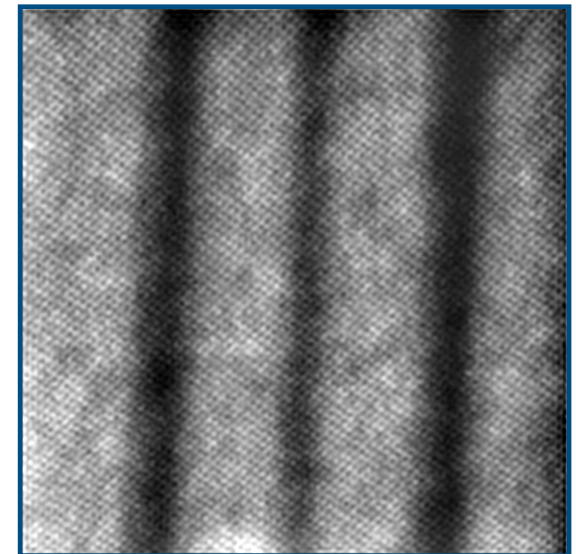
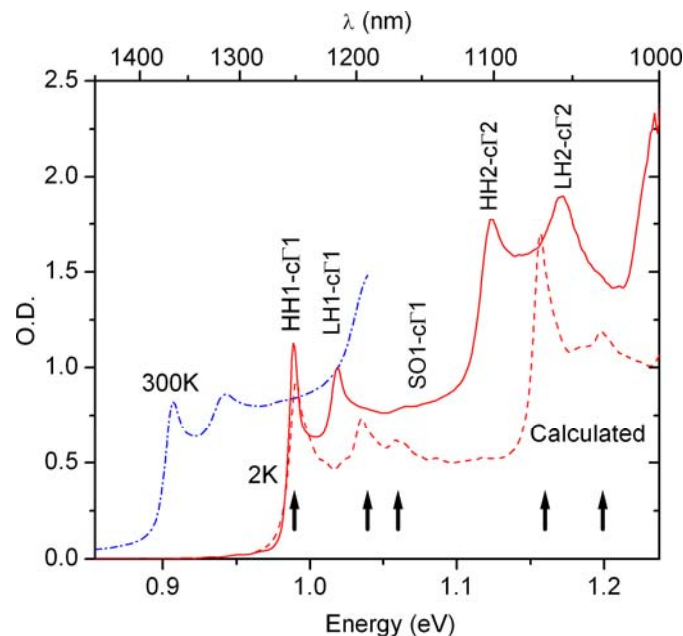
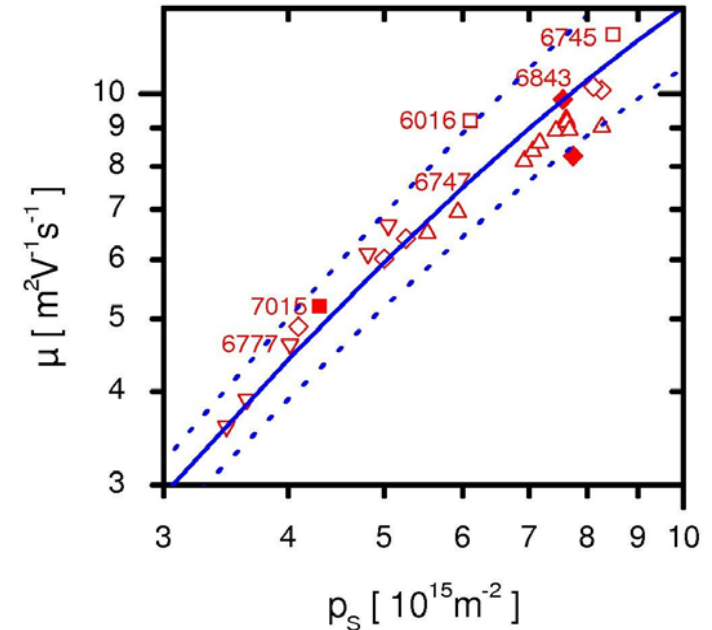


- Electrons emitted by a hot filament sustain a **DC plasma**
- Low ( $\sim 10\text{eV}$ ) ion energy
- Discharge confined by a magnetic field ( $\sim 1\text{mT}$ )
- **High deposition rates** 5-10nm/s in “High rate” regime

# LEPECVD for SiGe heterostructures deposition

Record mobility for p-type carrier in Ge quantum wells

SiGe superlattices with excellent structural/optical properties



# Prior knowledge of the LEPECVD plasma

## A few experimental results

Mass spectrometry for Ar:H<sub>2</sub> plasma: **ArH<sup>+</sup>** and **H<sub>3</sub><sup>+</sup>** most abundant species

## A (quite pictorial) educated guess

Ar ion bombardment removes the H atoms saturating the Si dangling-bonds



**High growth rates**

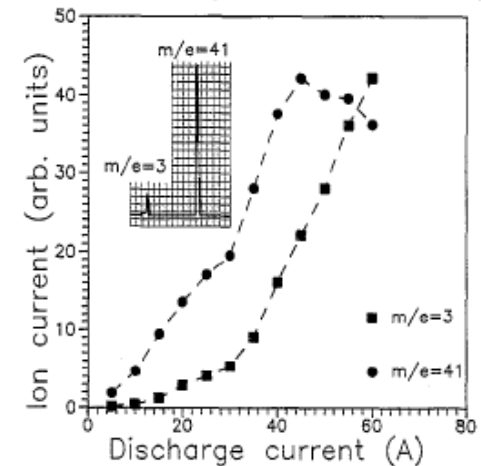
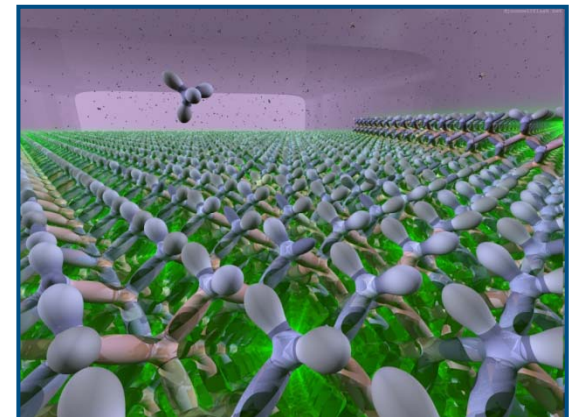


Fig. 4. The current of positively charged ions as a function of the discharge current. The inset shows the ion spectrum at a discharge current of 20 A.

N. Korner et al. Surface and Coatings Technology 76-77, 731 (1995)



# nc-Si deposition by LEPECVD

## Motivations

Low substrate temperature

High deposition rate 5-10nm/s for  
epitaxial material

## Objectives

Achieving the “right” microstructure

Dopant incorporation

Optimized procedure for device  
fabrication

Plasma monitoring



# nc-Si deposition by LEPECVD

## A wide spectrum research

Approx **120 depositions** performed on **five** different substrates:

**Si(100)**

**SiO<sub>2</sub>/Si(100)**

**glass**

**ITO/glass**

**ZnO/glass**

Varied growth parameters:

**SiH<sub>4</sub> dilution (%)**:  $\frac{[\text{SiH}_4]}{[\text{H}_2] + [\text{SiH}_4]}$

**SiH<sub>4</sub> flux**: 0.5 to 20sccm

**Plasma density** (through the confining magnetic field)

**Substrate temperature**: 200-300°C

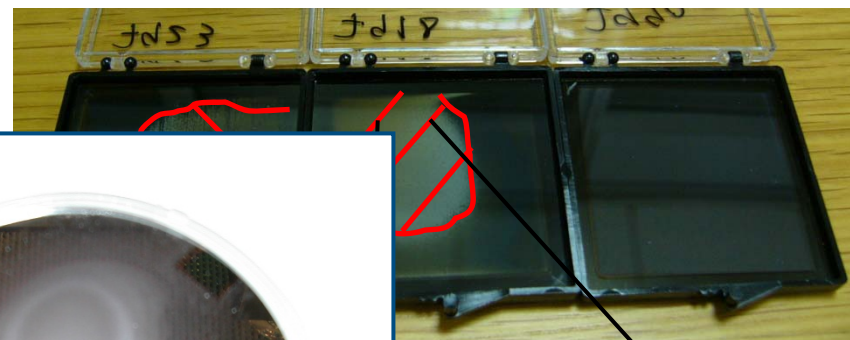


# Film adhesion

Under conditions developed for epitaxial Si deposition



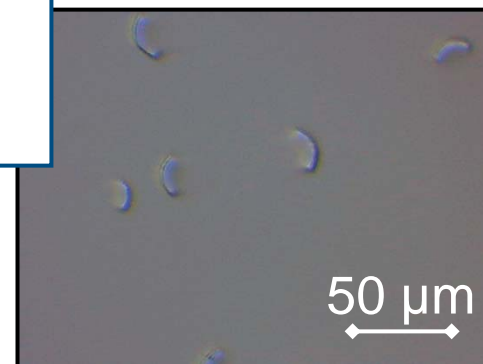
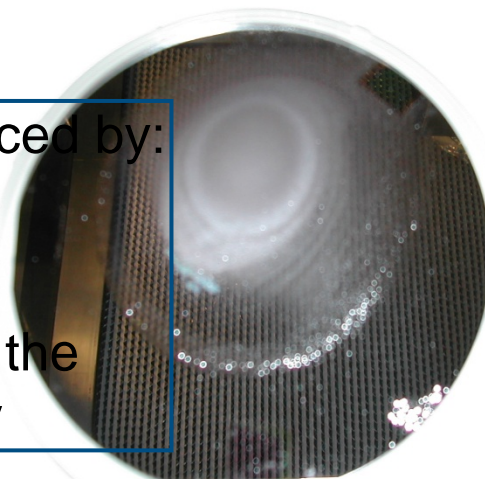
The film is **not sticking!** Extensive **flaking** due to internal stress



0.6mT

0.5mT

Adhesion is influenced by:  
Substrate **type** and  
**temperature**  
Strong influence of the  
**plasma density**



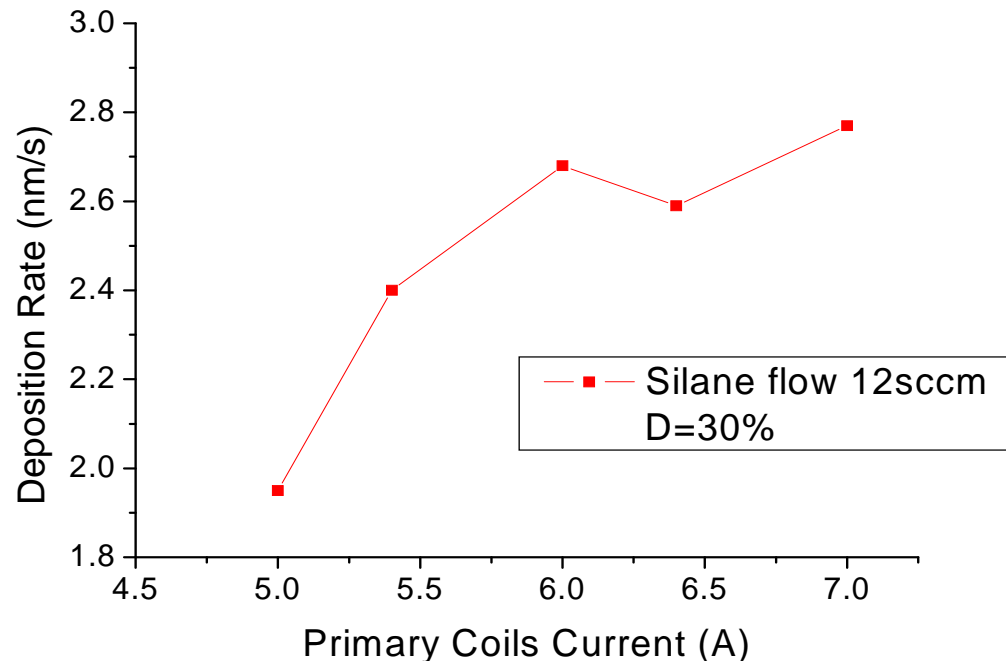
50  $\mu\text{m}$



# Film adhesion: role of the confining magnetic field

Reduction of the confining magnetic field

- ▲ improved film adhesion
- ▼ growth rate reduction



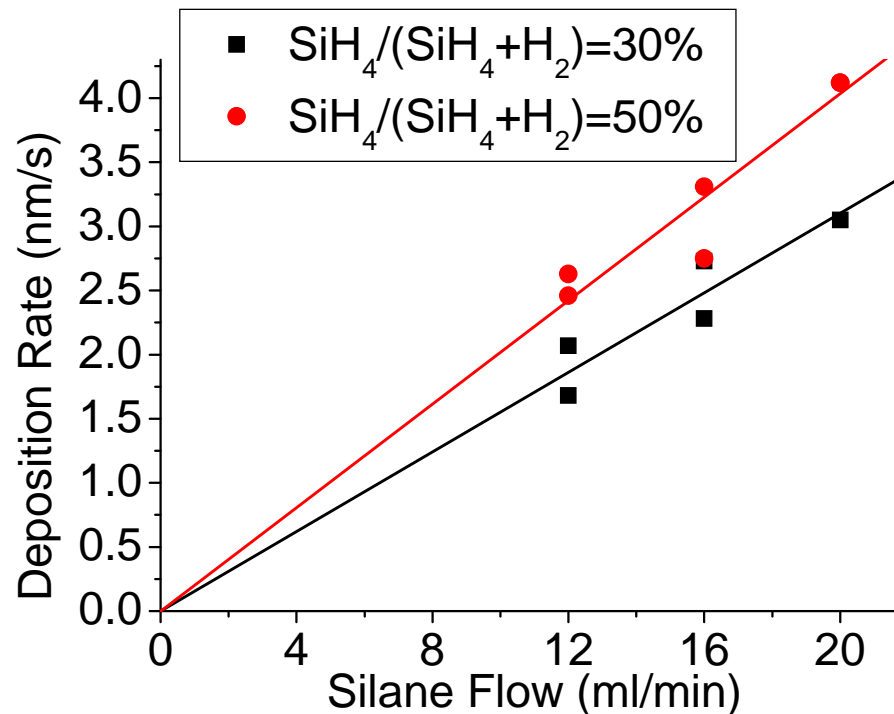
Confining field of 0.5mT (5A current) ensures a sufficiently **good adhesion** for all the substrates considered

# “H-etching” of nc-Si film

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Higher hydrogen content in the feed gas reduces the deposition rate



PRL 100, 046105 (2008)

PHYSICAL REVIEW LETTERS

week ending  
1 FEBRUARY 2008

## Thermal-Hydrogen Promoted Selective Desorption and Enhanced Mobility of Adsorbed Radicals in Silicon Film Growth

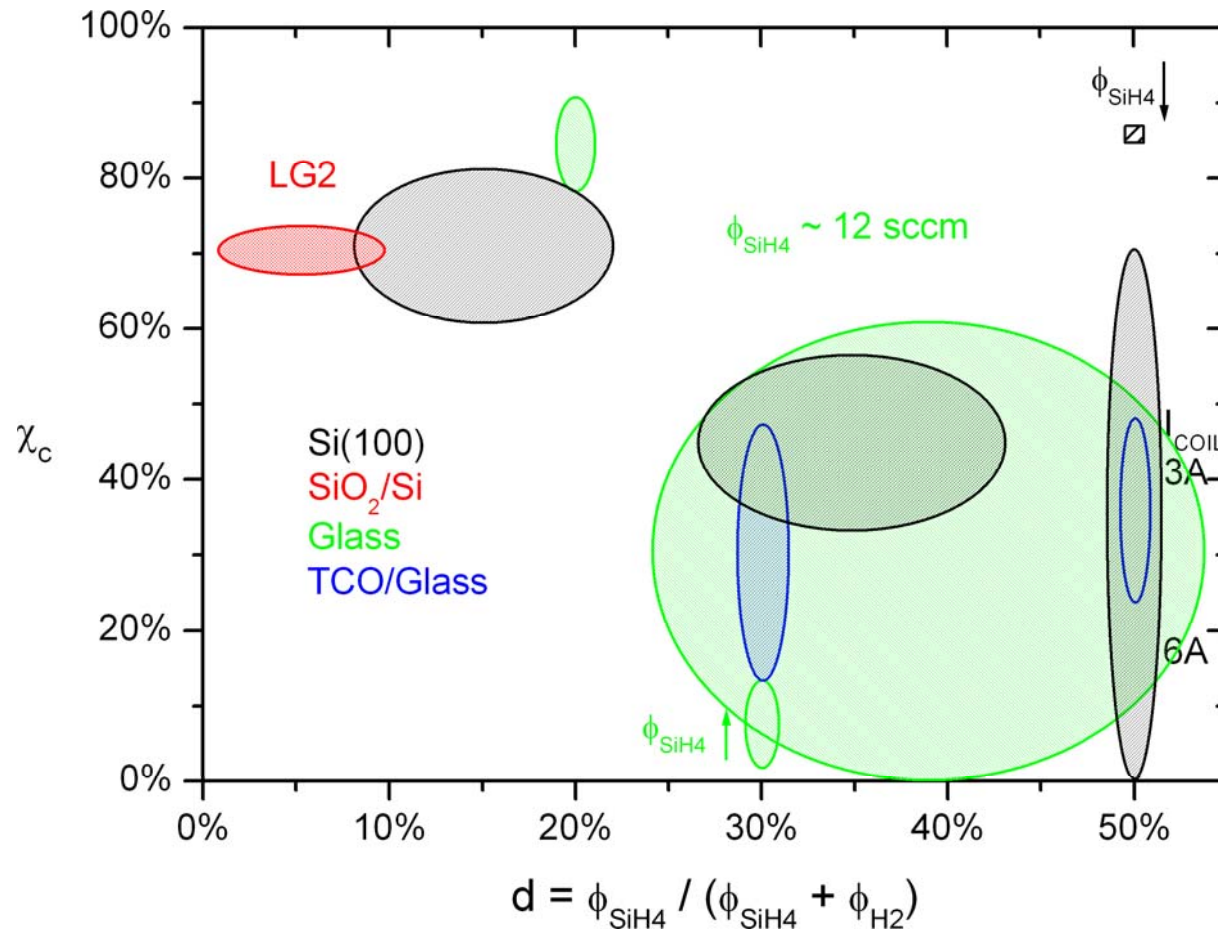
S. Cereda, F. Zipoli, M. Bernasconi, Leo Miglio, and F. Montalenti\*

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# Crystalline/amorphous fraction optimization

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Nanophoto  
final meeting  
21<sup>th</sup> November 2008  
Como

# Crystalline/amorphous fraction optimization

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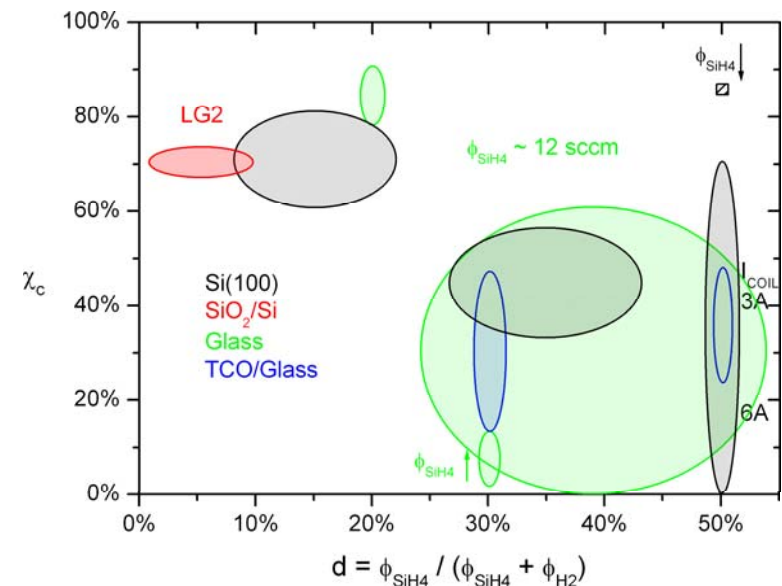


Great variability of the  $\chi_c$  especially around 30-40%

The “transition type” nc-Si is obtained at d value much higher than in radio-frequency PECVD for all substrate type



The specific character of the plasma might play a relevant role



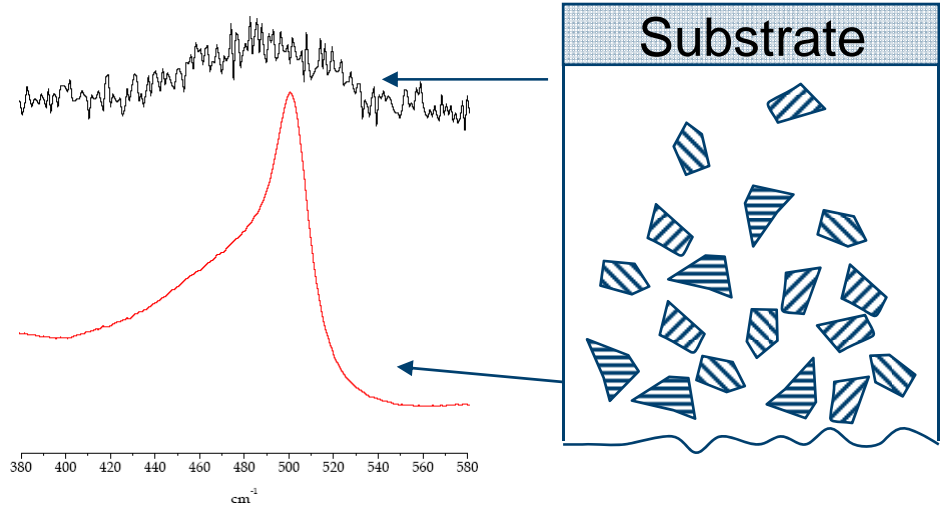
# Silane flow and uniformity in the growth direction

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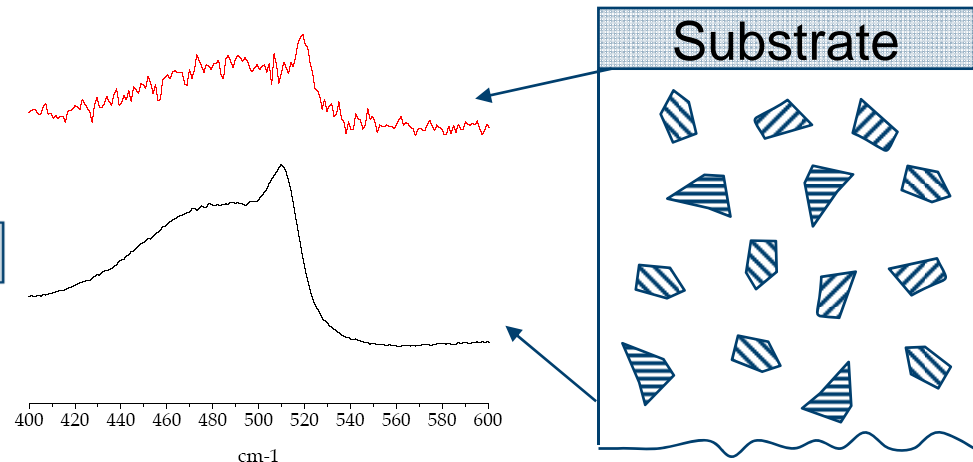


$\text{SiH}_4 = 20 \text{ sccm}$

Silane Concentration  
 $\text{SiH}_4/(\text{SiH}_4+\text{H}_2) = 30\%$



$\text{SiH}_4 = 12 \text{ sccm}$



Raman Spectra by A. Le Donne UNIMIB

## WP2- Task 1 Optimization of film microstructure

- Process window to obtain “transition type” nc-Si  
SiH<sub>4</sub> dilution  $\approx 30\%$   
SiH<sub>4</sub> flux  $\approx 12\text{sccm}$   
Confining field  $\approx 0.5\text{mT}$  (electron density  $10^{16}\text{ m}^{-3}$ )
- Good adhesion on all substrate investigated
- Good uniformity in the growth direction
- Bad “in plane” uniformity



# Doping of nc-Si layer

## Requirements for p-type layer in thin film Si solar cell

### Thin (30nm) and highly conductive

- I High dopant **incorporation**
- II High dopant **activation**
- III High **crystallinity**

### Things are made more complex by ...

- I incorporation does not depend monotonically on the dopant concentration in the feed gas
- II the low substrate temperature does not favour activation
- III Boron favours amorphization



# Doping of nc-Si layer : p-type layer

Two TCOs investigated

ITO – not compatible with H-plasma

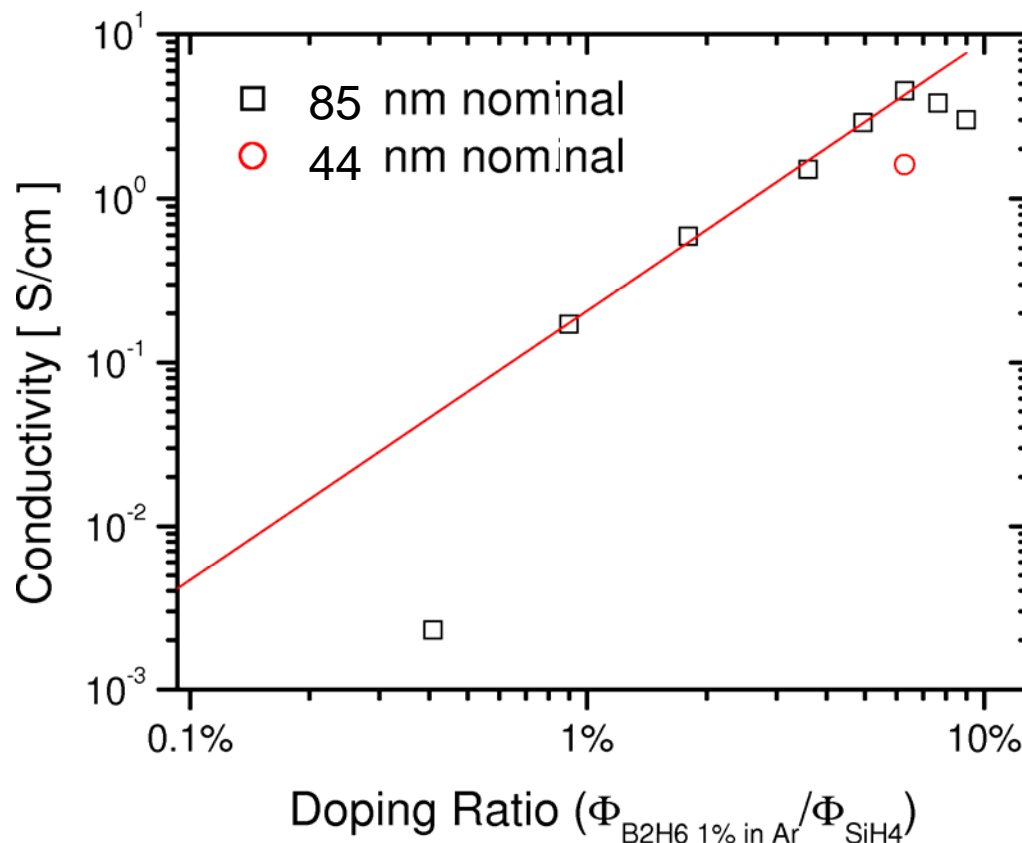
ZnO – good compatibility

Increased crystallinity

$\text{SiH}_4$  concentration = 1%

$\text{SiH}_4$  flux = 0.5sccm

Conductivity as a function of the Doping Ratio =  $\text{B}_2\text{H}_6/\text{SiH}_4$



Highest conductivity  
for DR=6.3%  
(DR<1% for PECVD)





# Doping of nc-Si layer : n-type layer

## Less critical than p-type

I **Not** necessarily **thin**

II High **crystallinity**

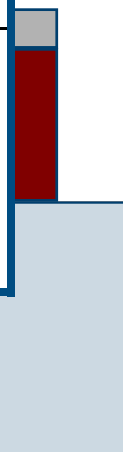
III Needs to be grown on the **absorbing layer**  
(crystallinity around 40-50%)

80nm n-type layer deposited in a  
different reactor

Absorption	Sample	DR	$\sigma_{RT}$ [ S.cm <sup>-1</sup> ]
	8151 / 56404	2.0%	0.008
	8152 / 56405	5.0%	0.01
	8153 / 56406	1.0%	0.02

Substrate: glass without TCO for  
electrical measurements

glass



## WP2- Task 2 Doping studies

### p-type layer

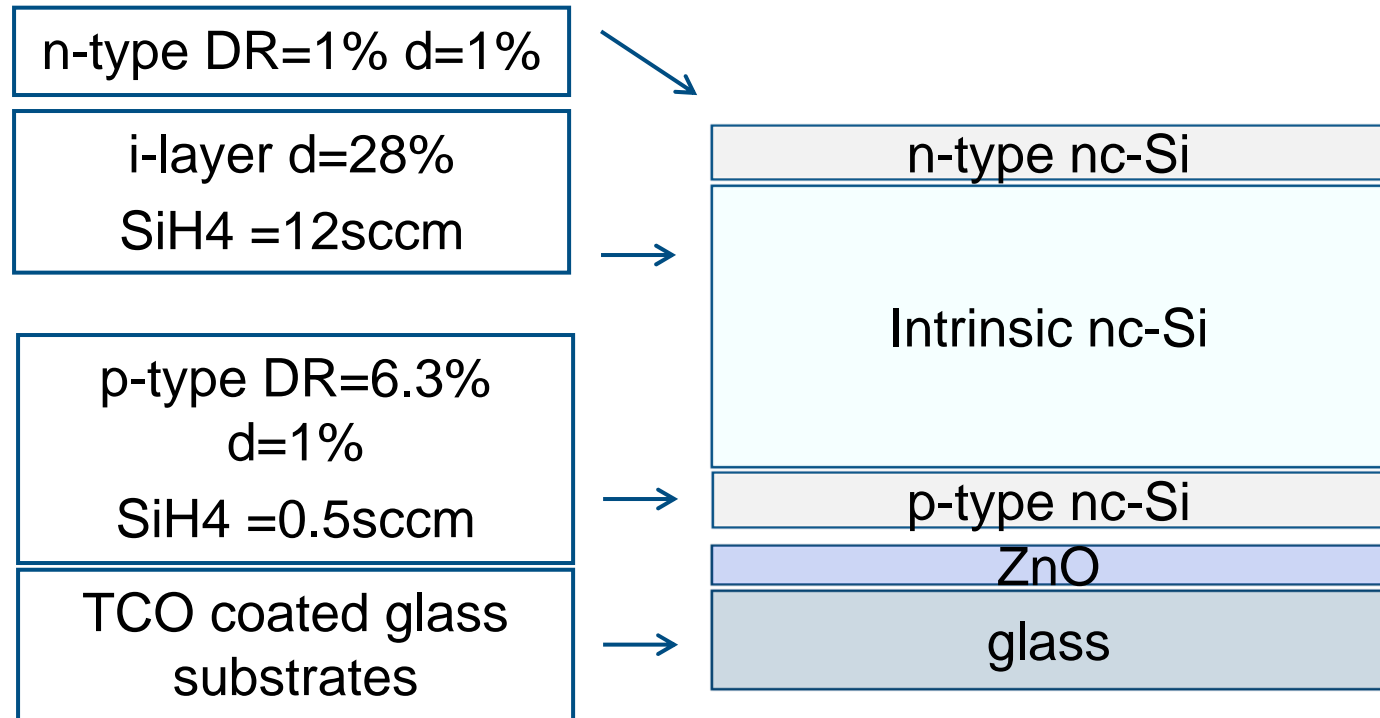
- State-of-the-art conductivity obtained
- Conductivity dependence on the doping ratio still under investigation

### n-type layer

- Conductivity sufficient for back-side contact
- Higher phosphine concentration in the doping mixture might be required for further improvement

# nc-Si growth for device optimization

Putting all the pieces together ...

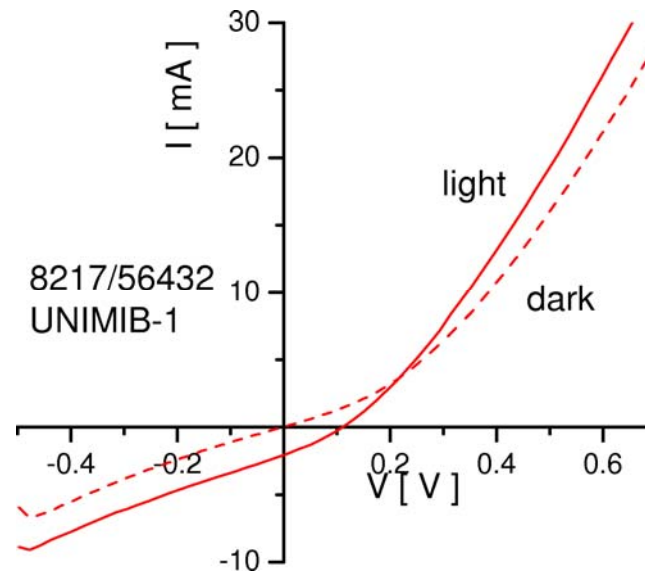


The result is ...



# nc-Si growth for device optimization

... much worse than the sum of the different components!

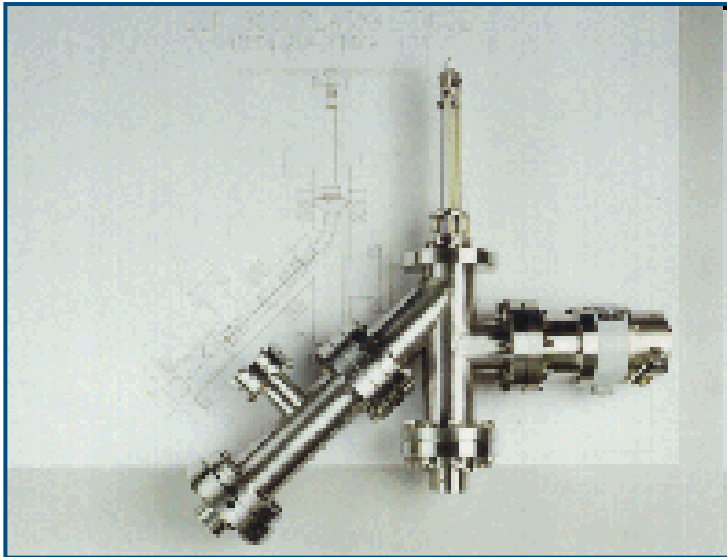


Poor photovoltaic performances:

- Low parallel and high series resistance related to fabrication issues
- Non optimized doped/undoped interfaces
- Recombination centers in the absorbing layer

# Plasma Monitoring: Mass spectrometry and Langmuir probe measurements

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EQP 300 from Hiden  
Analytics

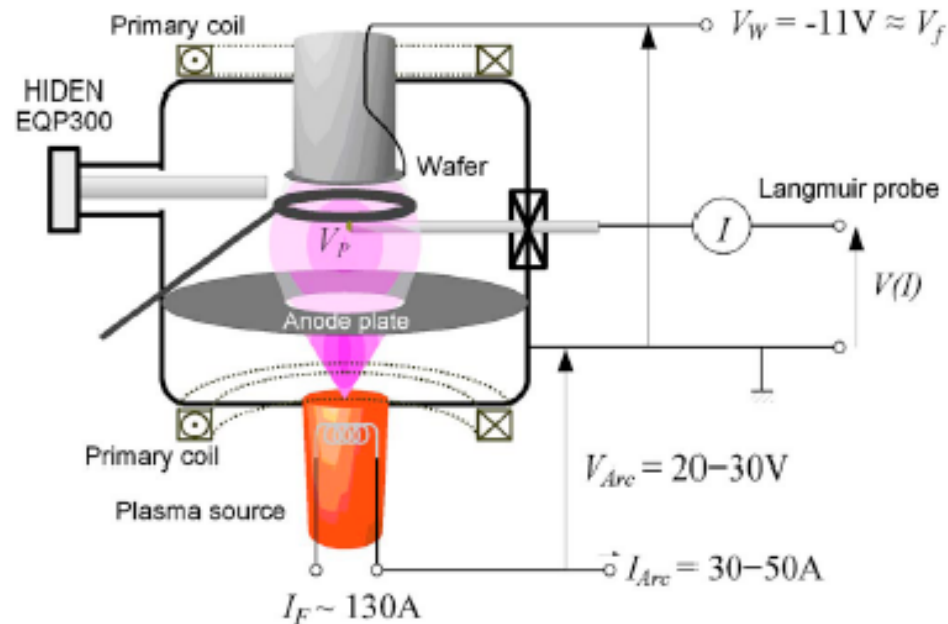
Mass/energy analyzer for  
ions and neutrals

EQP300 specially designed to:

monitor a DC plasma avoiding damage by the **1kW power** of  
the discharge

perform measurements at **different** radial **position** in the  
reactor

# Plasma Monitoring: Mass spectrometry and Langmuir probe measurements



**Energy integrated ion density** measured in secondary ions mass spectroscopy (**SIMS**) mode

**Neutral density** measured in threshold ionization mass spectroscopy (**TIMS**) mode

**Electron and ion current** and densities measured by Langmuir probe

# NANOPHOTO WP2 Objectives

**+**

**Optimization of film microstructure**  
Crystalline/amorphous ratio, grain size

**++**

**Doping studies**  
Dopant incorporation in the nc-Si layer

**-**

**nc-Si growth for device fabrication**  
Application of the optimized growth procedures to device fabrication

**++**

**Plasma diagnostics**  
Plasma diagnostic by mass spectrometry and Langmuir probe

